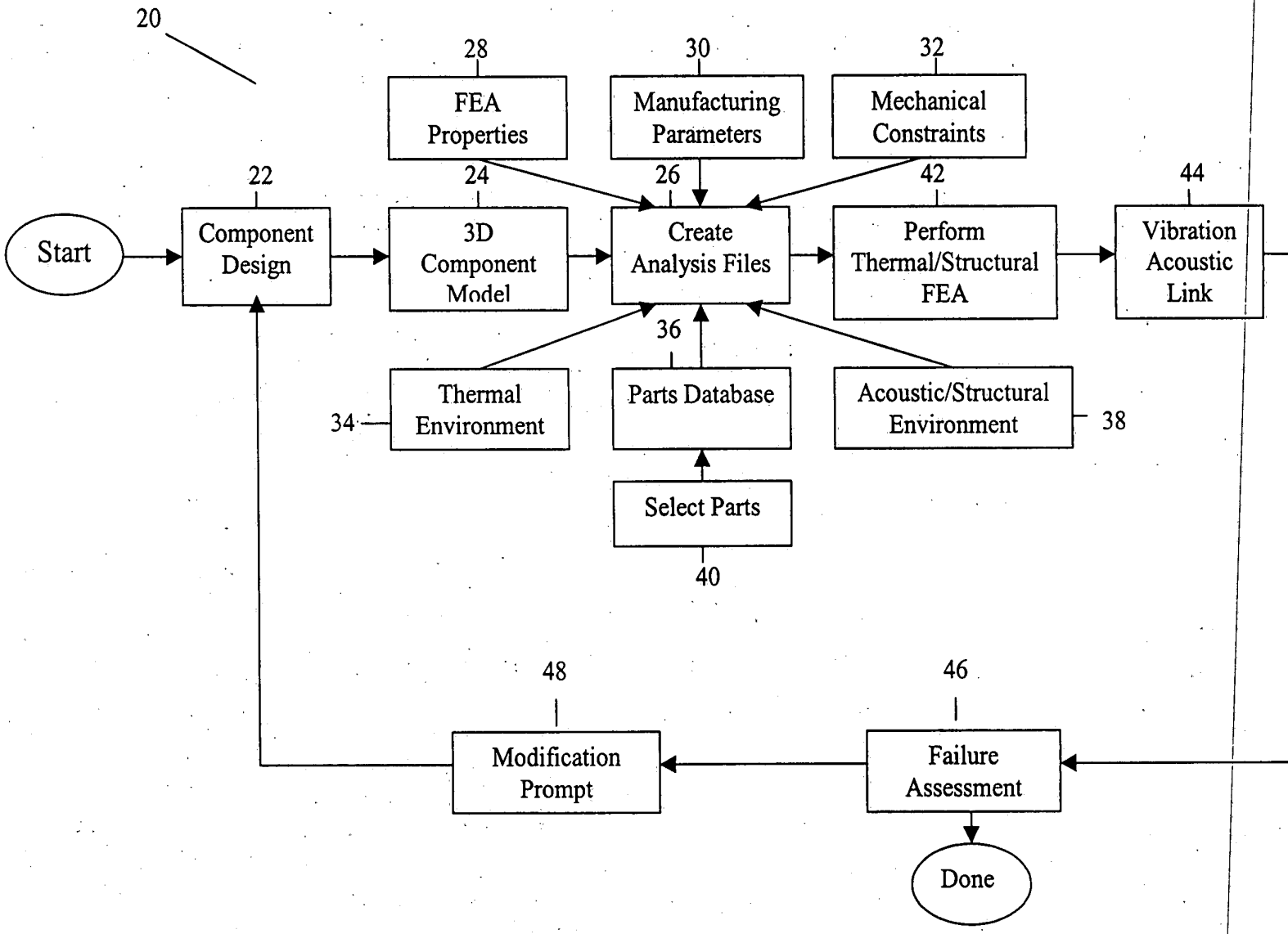
FIG. 1.



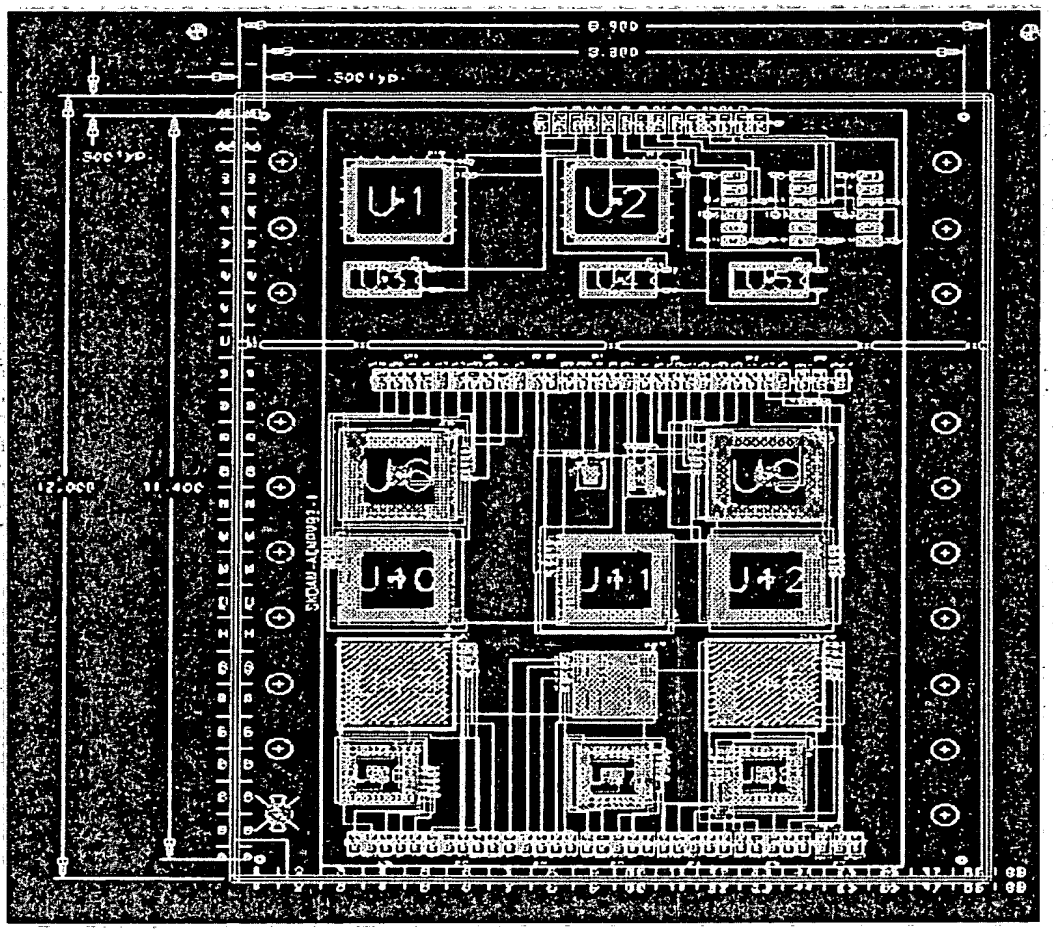

9.900
9.800
.500 typ.
.500 typ.
12.000
11.400
U1
U2
U3
U4
U5
U6
U7
U8
U9
U10
U11
U12

FIG. 2.

Figure 3

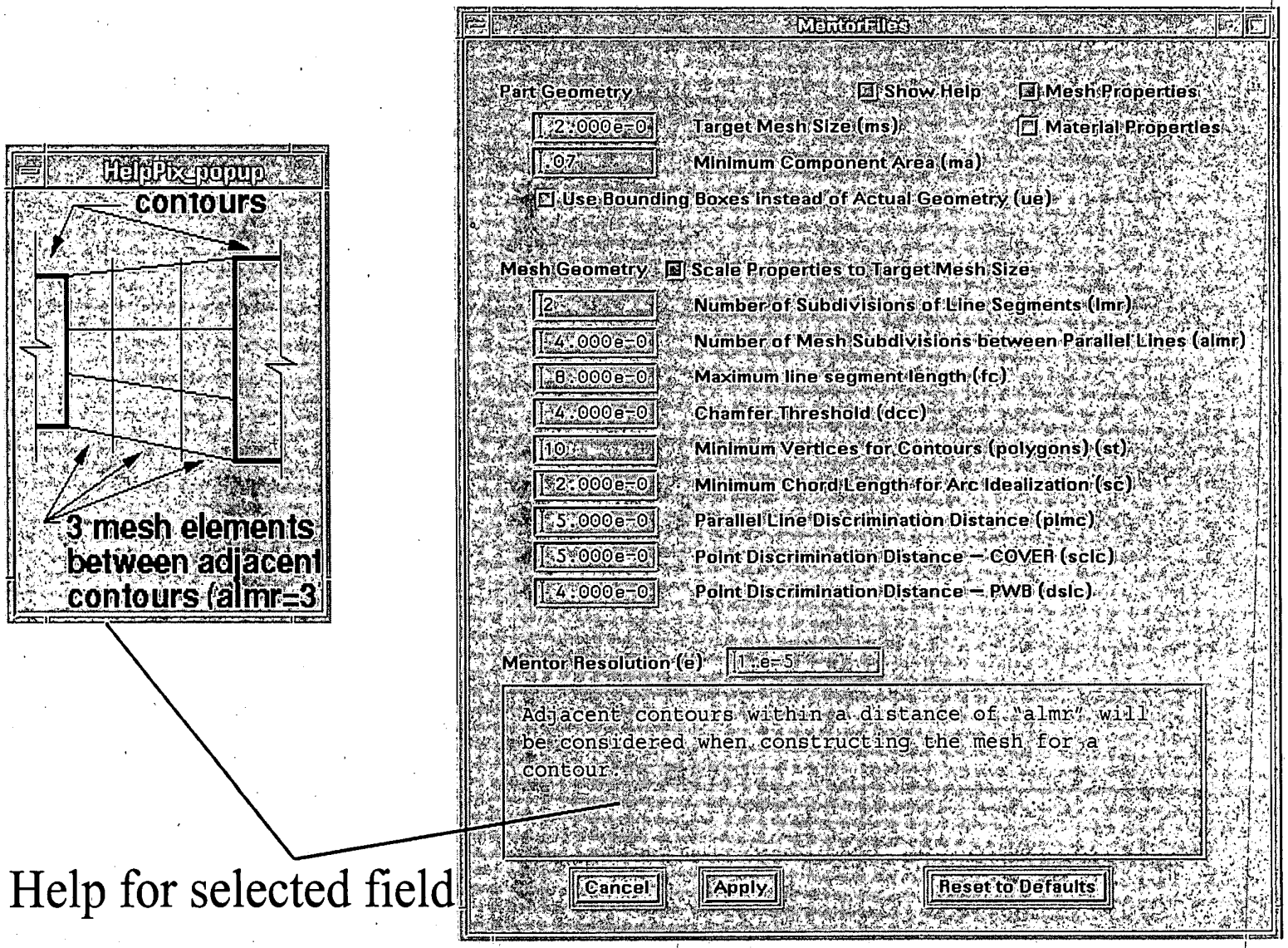
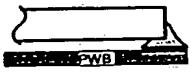
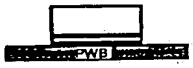
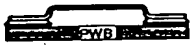
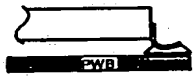
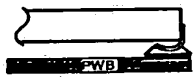
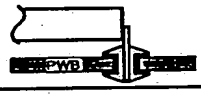


FIG. 4.

	Durability Module	Description	Configuration
	CCC	Leadless chip component	
54	DIO	Planar-diode package	
52	IND	Inductor feedthrough foil	
58	Hybrid-GW	Gull wing	
58	Hybrid-SGW	Spider gull wing	
56	L-lead	L-leaded component	
56	J-lead	J-leaded component	
	PTH	Plated-through-hole component	
59	PBGA	Plastic ball grid arrays	

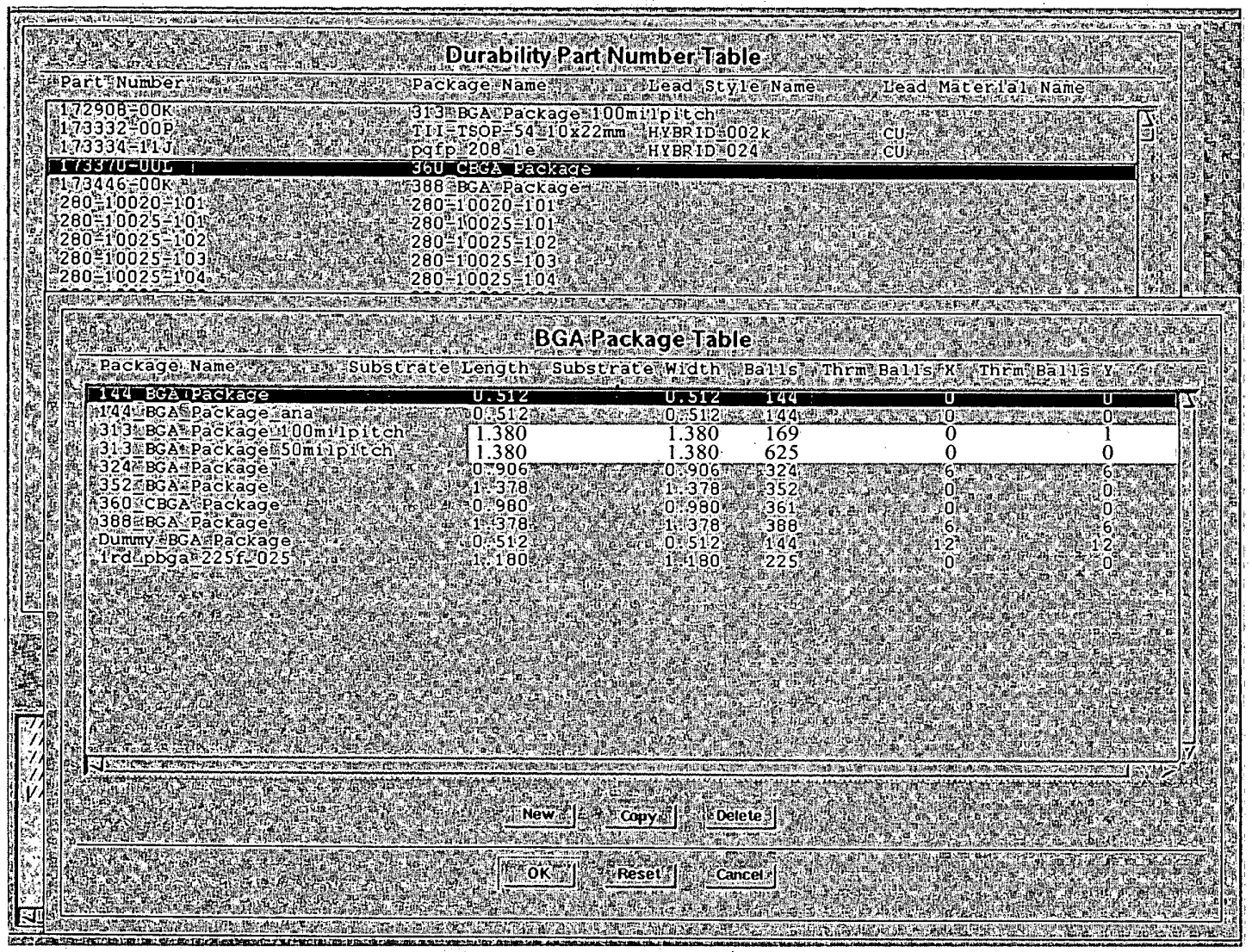


FIG. 5.

Title: *Method, System and Computer Program Product for Multidisciplinary Design Analysis of Structural Components*
Inventor: Mostafa Rassaian
Application No: To be assigned
Atty Dkt No: 38190/235695

Title: *Method, System and Computer Program Product for Multidisciplinary Design Analysis of Structural Components*
Inventor(s): Mostafa Rassaian
Application No: To be assigned
Atty Dkt No: 38190/235695

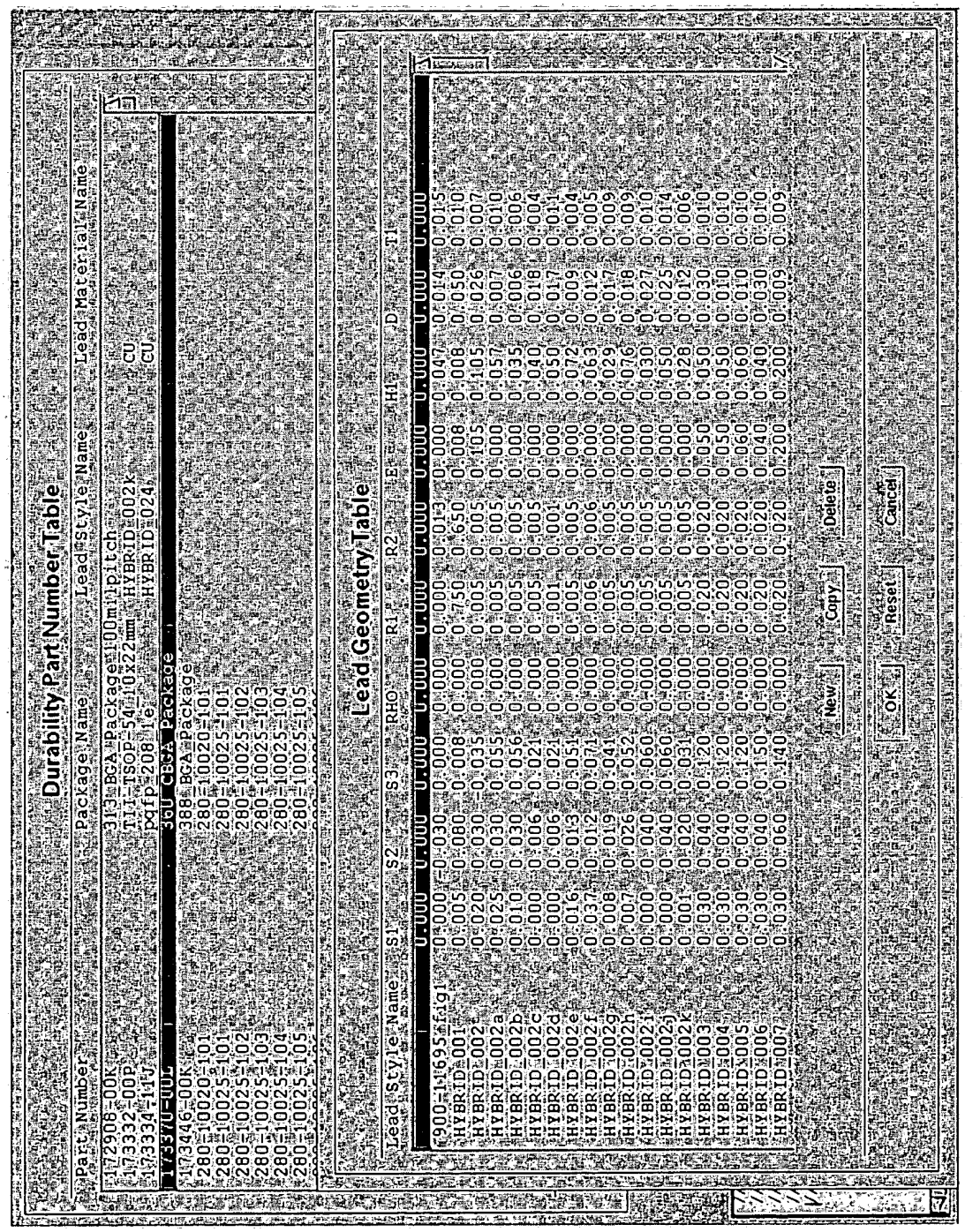


FIG. 6.

Title: *Method, System and Computer Program Product for Multi[redacted]ciplinary Design Analysis of Structural Components*
Inv[redacted]: Mostafa Rassaian
App[redacted]on No: To be assigned
Atty Dkt No: 38190/235695

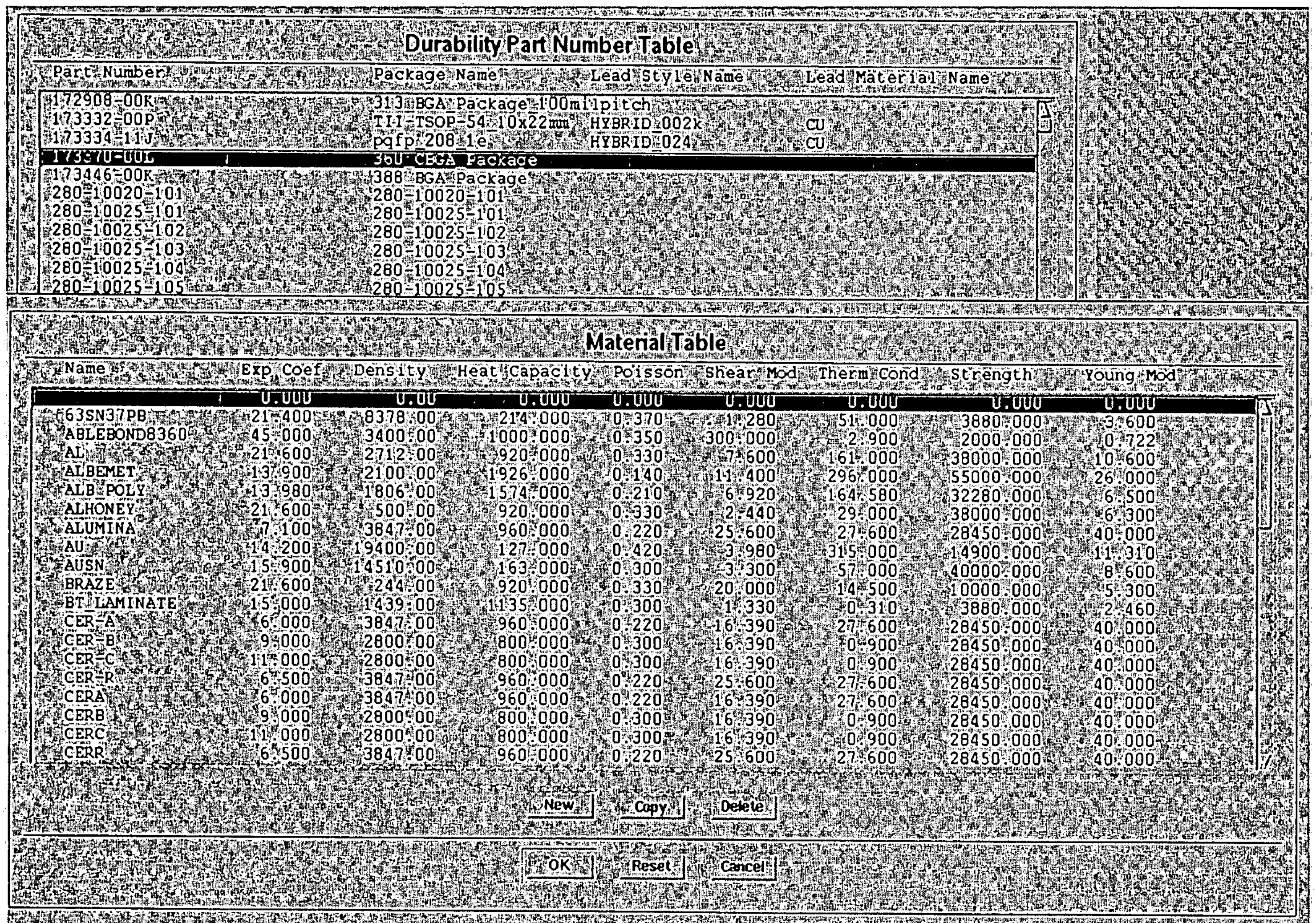


FIG. 7.

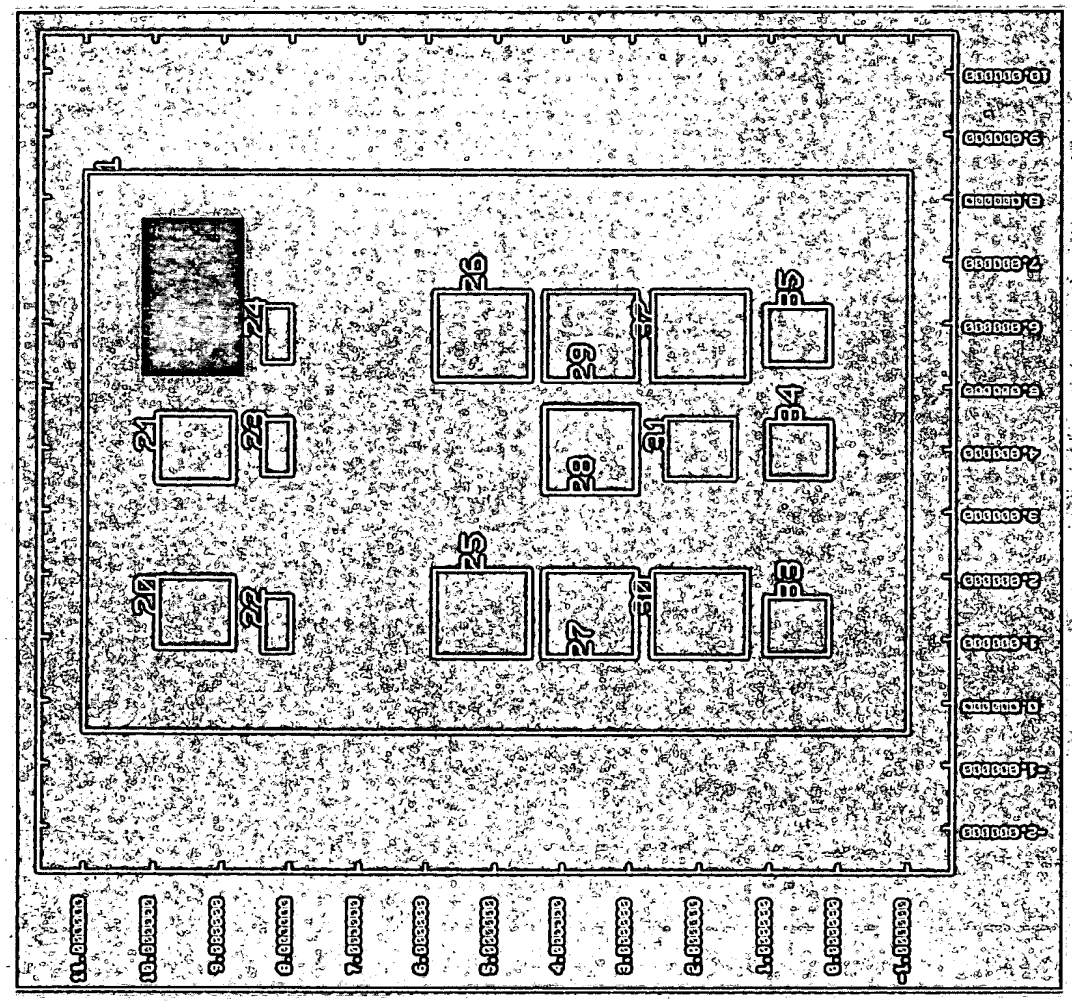

1
2
3
4
5
6
7
8
9
10
11
12
13
14
15
16
17
18
19
20
21
22
23
24
25
26
27
28
29
30
31

FIG. 8.

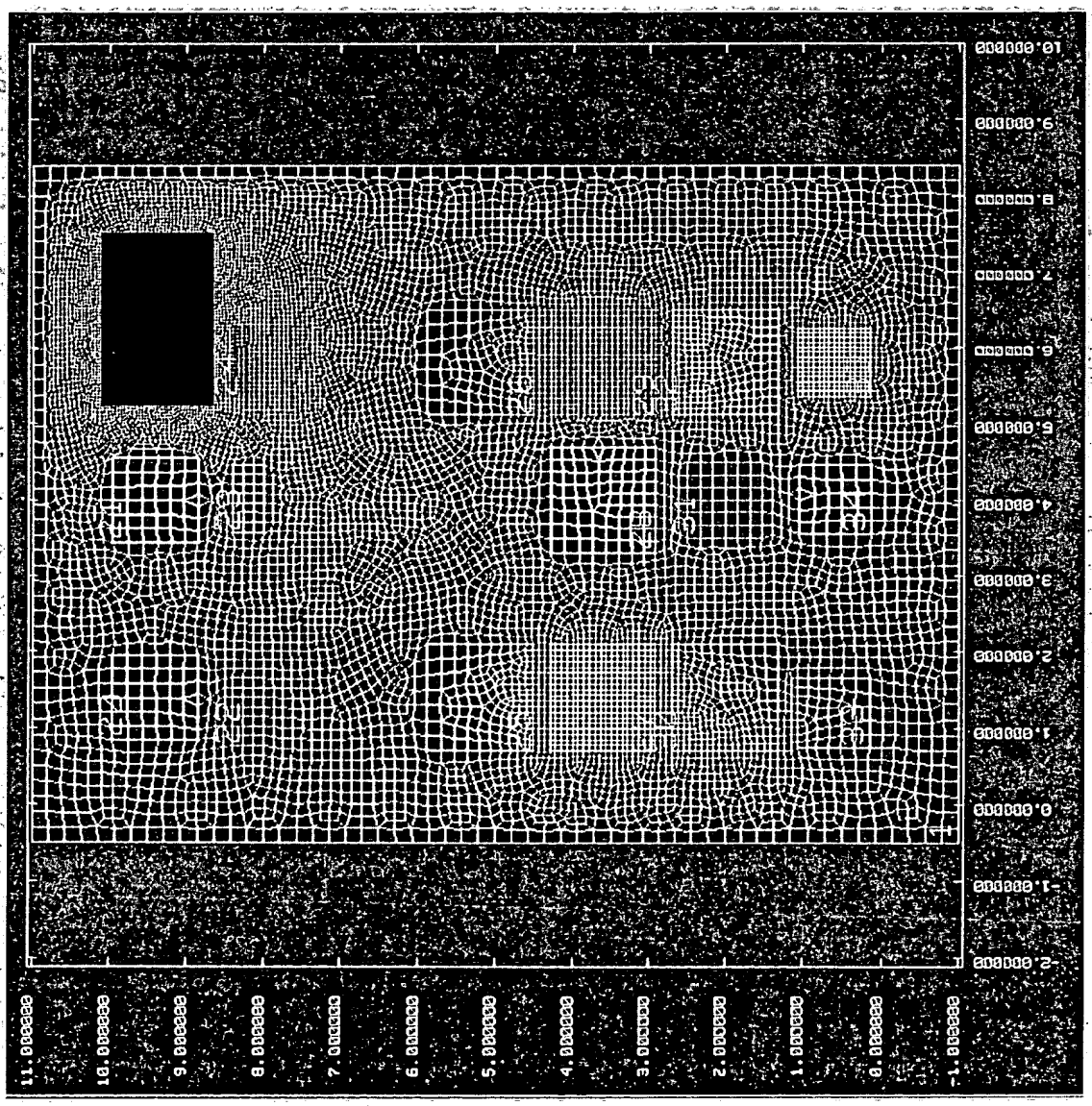
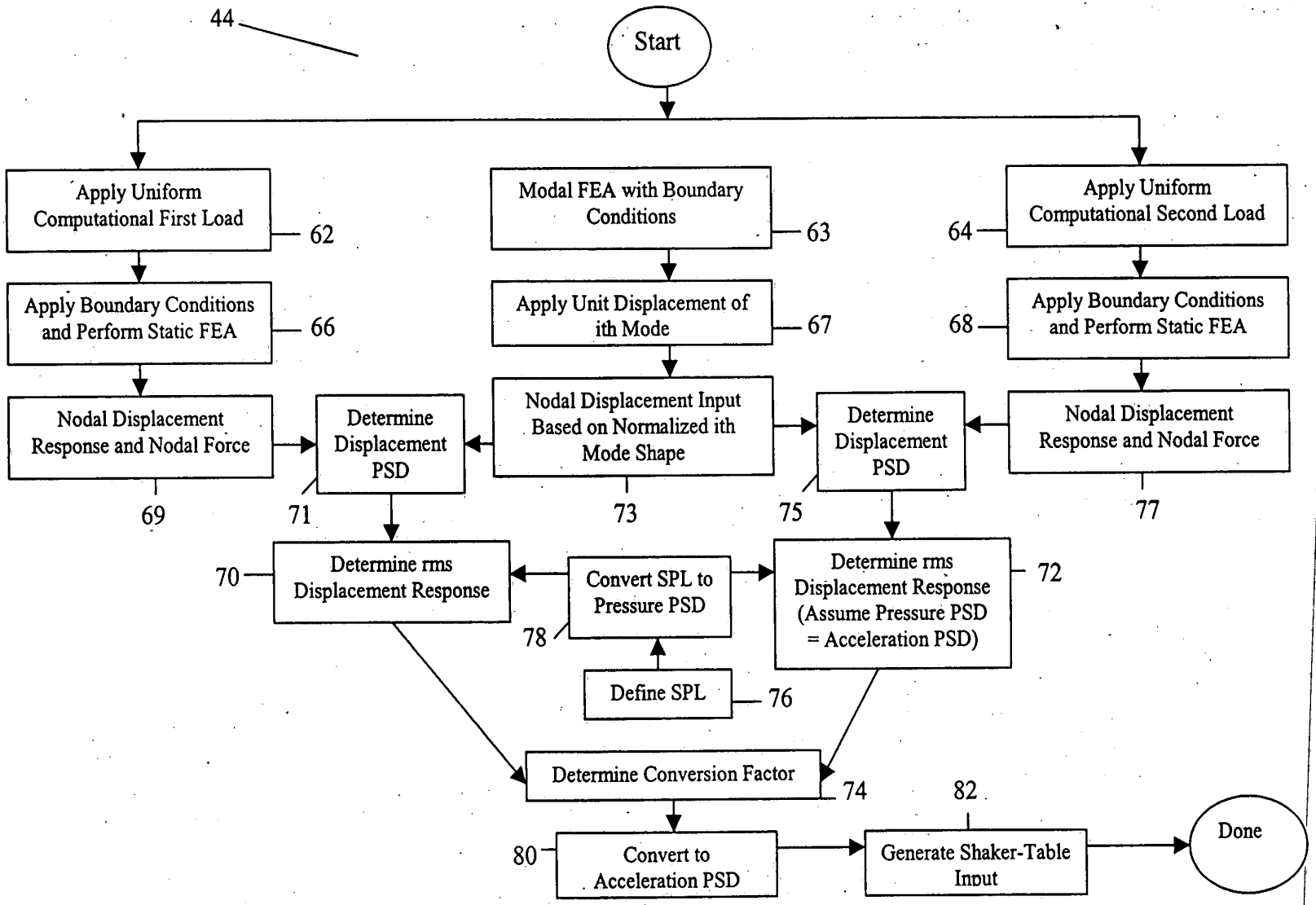

11.000000
10.000000
9.000000
8.000000
7.000000
6.000000
5.000000
4.000000
3.000000
2.000000
1.000000
0.000000
-1.000000
10.000000
9.000000
8.000000
7.000000
6.000000
5.000000
4.000000
3.000000
2.000000
1.000000
0.000000
-1.000000
-2.000000

FIG. 9.

FIG. 10.



Title: *Method, System and Computer Program Product for Multidisciplinary Design Analysis of Structural Components*
Inventor(s): Mostafa Rassaian
Application No: To be assigned
Atty Dkt No: 38190/235695

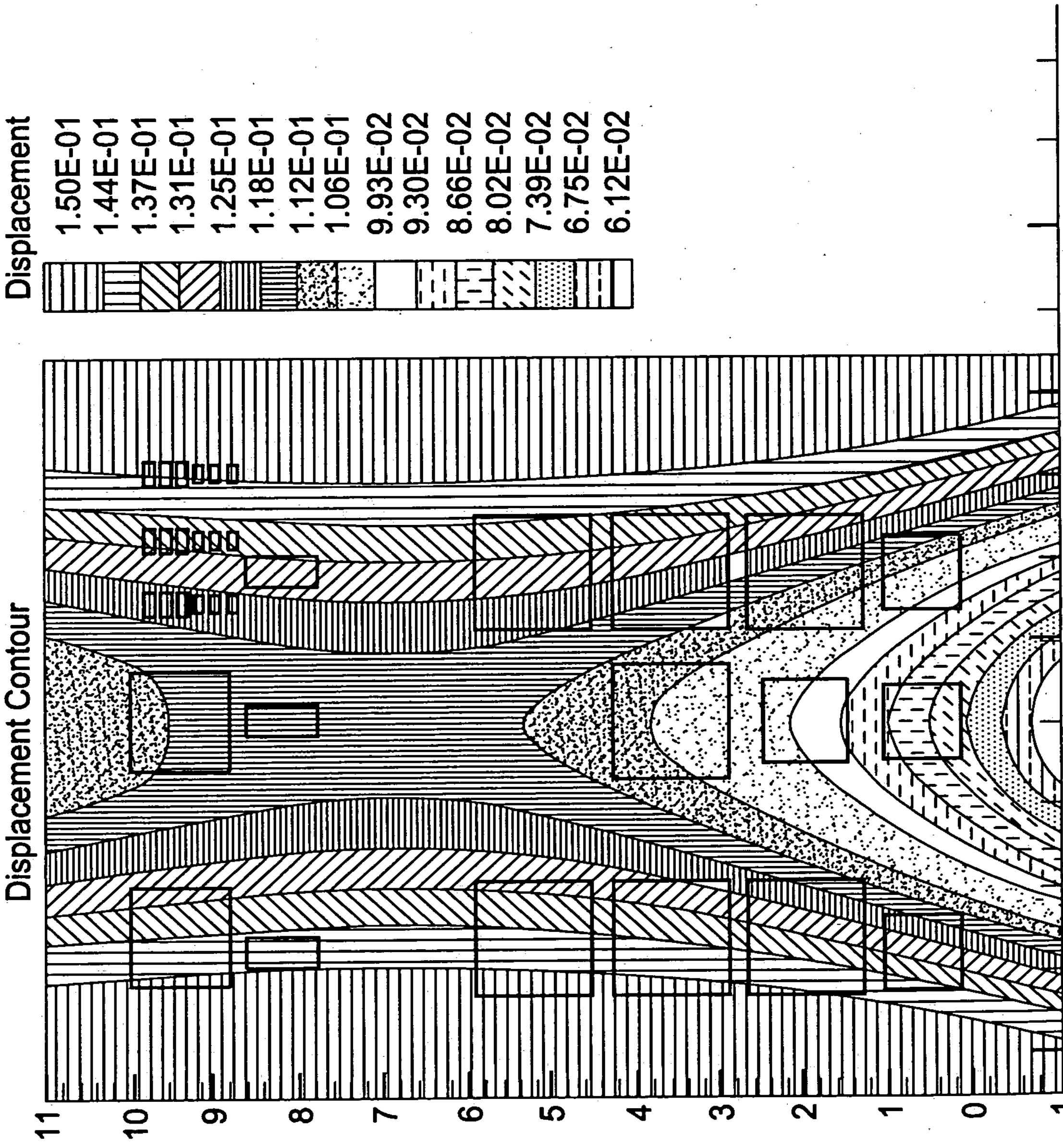
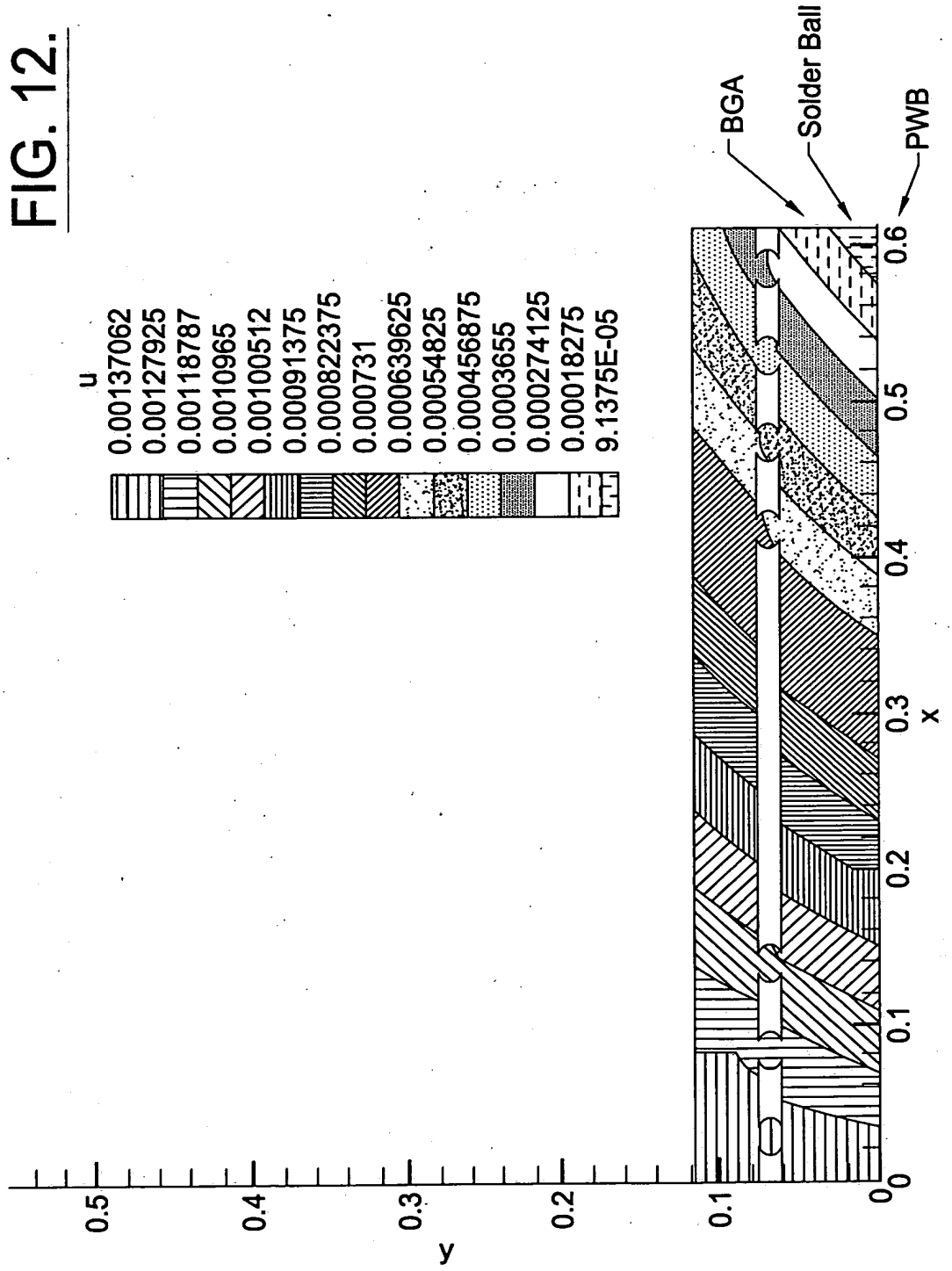


FIG. 11.

FIG. 12.


u
0.00137062
0.00127925
0.00118787
0.0010965
0.00100512
0.00091375
0.000822375
0.000731
0.000639625
0.00054825
0.000456875
0.0003655
0.000274125
0.00018275
9.1375E-05
BGA
Solder Ball
PWB
x
y
0
0.1
0.2
0.3
0.4
0.5
0.6

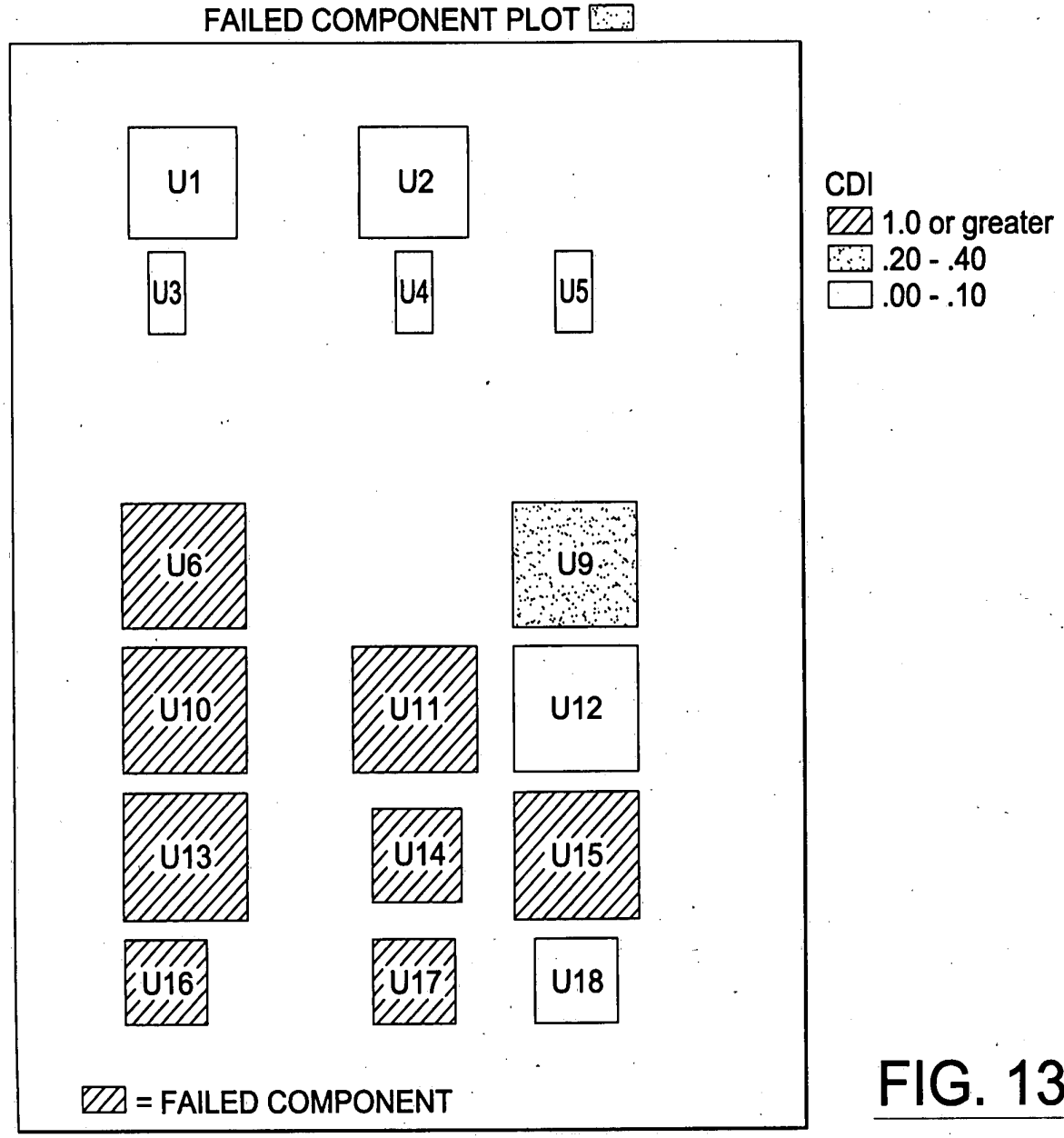


FIG. 13.